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APPLICANTS
Levchik et al.FILING DATE
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GROUP ART UNIT

U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
RS	6214455	04/01	Honda et al.			
RS	5945222	08/99	Nagase et al.			
RS	6005064	12/99	Hirai et al.			

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
RS		03/029 258	04/03	International				
RS		0451101	10/91	European				
RS		01/74960	10/01	International				
RS		03/029258	04/03	International				
RS		02/072655	09/02	International				
RS		1 116 774	07/01	European				
RS		02/055 603	07/02	International				
RS		08-183835	07/96	Japan				
RS		2000-256633	09/2000	Japan				

OTHER PRIOR ART (Including Author, Title, Date, Pertinent Pages, Etc.)

RS	*	1.	Database WPI Section Ch, Week 200143, Derwent Publications Ltd., London, GB; Class A21, An2001-400810 XP002274895 & JP2001-019746, 23, January 2001
RS	*	2.	Database WPI Section Ch, Week 200230, Derwent Publications Ltd., London, GB; Class A21, An2002-246988, XP002274896 & JP2001-302879, 31, October 2001
RS	*	3.	Database WPI Section Ch, Week 200105, Derwent Publications Ltd., London, GB; Class A21, An2001-034272, XP002274897 & JP2000-226499, 15, August 2000
RS		4.	Takeda et al., "Environment-Friendly, Halogen-Free Material for PCBs," pp. S11-4-1- to S11-4-5, Presented at IPC Printed Circuits Expo®2001
RS	*	5.	Liu et al., "Flame-Retardant Epoxy Resin from o-Cresol Novolac Epoxy Cured with a Phosphorus-Containing Aralkyl Novolac"; Journal of Polymer Science, Part A: Polymer Chemistry Vol. 40,2329-2339(2002)

EXAMINER

/Robert Sellers/

DATE CONSIDERED

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* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609.
Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.